

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (canceled).

Claim 9 (previously presented): A laminated ceramic electronic component comprising:

a ceramic laminated member;

an inner conductor provided inside of the ceramic laminated member;

an outer electrode provided on the surface of the ceramic laminated member;

and

a lead conductor connecting the inner conductor to the outer electrode; wherein

a thickness of the lead conductor is less than a thickness of the inner conductor;

and

the lead conductor is defined by a plurality of lead conductor layers that overlap and are in contact with each other.

Claim 10 (previously presented): The laminated ceramic electronic component according to claim 9, wherein a conductor width of the lead conductor is greater than a conductor width of the inner conductor.

Claim 11 (previously presented): The laminated ceramic electronic component according to claim 9, wherein the inner conductor defines a coil.

Claim 12 (previously presented): The laminated ceramic electronic component according to claim 9, wherein the inner conductor includes a plurality of inner conductor pattern layers and the number of lead conductor pattern layers of said plurality of lead conductor pattern layers is less than the number of inner conductor pattern layers of

said plurality of inner conductor pattern layers.

Claim 13 (previously presented): The laminated ceramic electronic component according to claim 9, wherein a metal content of the lead conductor is greater than a metal content of the inner conductor.

Claim 14 (previously presented): The laminated ceramic electronic component according to claim 9, wherein the thickness of the inner conductor is in the range of about 70 μm to about 80 μm , and the thickness of the lead conductor is in the range of about 35 μm to about 40 μm .

Claim 15 (previously presented): The laminated ceramic electronic component according to claim 12, wherein the number of inner conductor pattern layers is 10 and the number of lead conductor pattern layers is 5.

Claim 16 (previously presented): The laminated ceramic electronic component according to claim 12, wherein at least one of the inner conductor pattern layers is made of a conductive paste including resin particles having thermal decomposition characteristics sufficient such that the resin particles are consumed when subjected to firing.

Claim 17 (previously presented): The laminated ceramic electronic component according to claim 12, wherein each of the plurality of inner conductor pattern layers is substantially U-shaped.

Claim 18 (previously presented): The laminated ceramic electronic component according to claim 12, wherein the inner conductor is a spiral coil.

Claims 19-27 (canceled).